

DOCKET NUMBER: 213480US0/pmh

DEC 19 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICATION OF:

Sei TSUNODA, et al.

: GROUP: 2812

SERIAL NUMBER: 09/942,626

: ATTENTION:

Application Division

Customer Corrections

FILED: AUGUST 31, 2001

FOR: LOW DIELECTRIC CONSTANT MATERIAL HAVING THERMAL RESISTANCE,  
INSULATION FILM BETWEEN SEMICONDUCTOR LAYERS USING THE SAME,  
AND SEMICONDUCTOR DEVICE

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

The Patent Office is requested to provide a corrected Official Filing Receipt for the attached. If you have any questions, please do not hesitate to contact us.

No fees are required. However, in the event that a fee is required, please charge the appropriate amount to our Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.



Norman F. Oblon  
Attorney of Record  
Registration Number 24,618



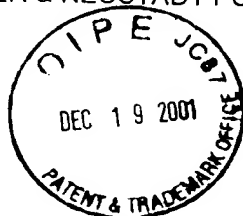
**22850**

Tel. (703) 413-3000  
Fax. (703) 413-2220  
(OSMMN 10/98)

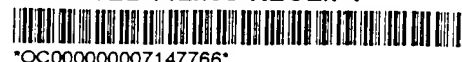


APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/942,626	08/31/2001	2812	840	213480US0		3	1

22850  
OBLON SPIVAK MCCLELLAND MAIER & NEUSTADT PC  
FOURTH FLOOR  
1755 JEFFERSON DAVIS HIGHWAY  
ARLINGTON, VA 22202



CONFIRMATION NO. 8767  
UPDATED FILING RECEIPT



\*OC000000007147766\*

Date Mailed: 12/03/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

**Applicant(s)**

Sei Tsunoda, Tokyo, JAPAN;  
Hideharu Nobutoki, Tokyo, JAPAN;  
Noboru Mikami, Tokyo, JAPAN;

**Assignment For Published Patent Application**

mitsubishi denki kabushiki kaisha, Chiyoda-ku, JAPAN;

**Domestic Priority data as claimed by applicant**

**Foreign Applications**

JAPAN 153600 / 1999 01/06/1999

If Required, Foreign Filing License Granted 10/22/2001

Projected Publication Date: 03/14/2002

Non-Publication Request: No

Early Publication Request: No

**Title**

Low dielectric constant material having thermal resistance, insulation film between semiconductor layers using the same, and semiconductor device

**Preliminary Class**

438

PLEASE NOTE THAT THE FOREIGN APPLICATION INFORMATION IS NOT BEING CLAIMED.

DELETE: JAPAN 153600/1999 01/06/99

RECEIVED  
DEC 05 2001

RECEIVED  
FEB 11 2002  
TC 1700

OBLON, SPIVAK, MCCLELLAND,  
& NEUSTADT, P.C.